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December 14, 2000

To: Commissioner of Patents and Trademarks  
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572  
20 McIntosh Drive  
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/679,514 10/06/00

Hung-Jen Hsu, Yu-Kung Hsiao,  
Chih-Kung Chang, Sheng-Liang Pan,  
Kuo-Liang Lu

A METHOD TO IMPROVE PASSIVATION  
OPENINGS BY REFLOW OF PHOTORESIST  
TO ELIMINATE TAPE RESIDUE

Grp. Art Unit:  
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#### INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation  
In An Application.

The following Patents and/or Publications are submitted to  
comply with the duty of disclosure under CFR 1.97-1.99 and  
37 CFR 1.56. Copies of each document is included herewith.

U.S. Patent 5,063,655 to Lamey et al., "Method to  
Integrate Drive/Control Devices and Ink Jet on Demand Devices  
in a Single Printhead Chip", teaches a method to integrate the  
driver pulse circuitry and the resistors of an ink jet printer  
onto the printer head.

U.S. Patent 5,731,243 to Peng et al., "Method of Cleaning Residue on a Semiconductor Wafer Bonding Pad", teaches a method to reduce protective tape adhesive contamination.

U.S. Patent 6,060,378 to Rolfson, "Semiconductor Bonding Pad for Better Reliability", discloses a method to form bonding pads with improved reliability.

U.S. Patent 6,025,275 to Efland et al., "Method of Forming Improved Thick Plated Copper Interconnect and Associated Auxiliary Metal Interconnect", discloses a method to form thick plated copper interconnects.

Sincerely,



Stephen B. Ackerman,  
Reg. No. 37761